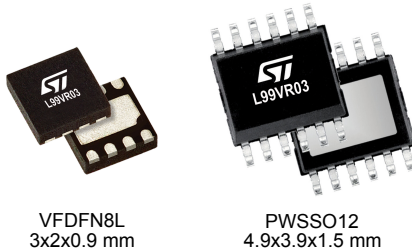


Automotive low dropout linear voltage regulator having 300 mA of current capability


 VFDFN8L
3x2x0.9 mm

 PWSSO12
4.9x3.9x1.5 mm

Features

Max. supply voltage	V_S	40 V
Output current	I_O	300 mA
Quiescent current	I_{qn}	800 nA ⁽¹⁾
		3.5 μ A ⁽²⁾

1. Maximum value with regulator disabled.
2. Maximum value with regulator enabled.

Product status link

[L99VR03](#)

Product summary

Order code	Package	Packing
3.3 V output voltage		
L99VR033QTR	VFDFN8L	Tape and reel
L99VR033PTR	PWSSO12	
5 V output voltage		
L99VR035QTR	VFDFN8L	Tape and reel
L99VR035PTR	PWSSO12	

- AEC-Q100 qualified
- Wide input voltage range up to 40 V
- Low quiescent current consumption
- Output voltage options: 3.3 V or 5 V
- Output voltage precision $\pm 2\%$ in all operating conditions
- Enable input for enabling/disabling the voltage regulator
- Thermal shutdown and short-circuit current limitation
- Undervoltage-lockout UVLO
- Wide operating temperature range $T_J = -40\text{ }^{\circ}\text{C}$ to $175\text{ }^{\circ}\text{C}$
- Sustaining slow ramp-up applications
- Supply voltage rejection: $> 60\text{ dB}$ at 1 kHz
- Performant line and load regulation

Application

- Automotive MCU power supplies
- Body control modules
- Telematics control units
- Automotive head units
- Headlights

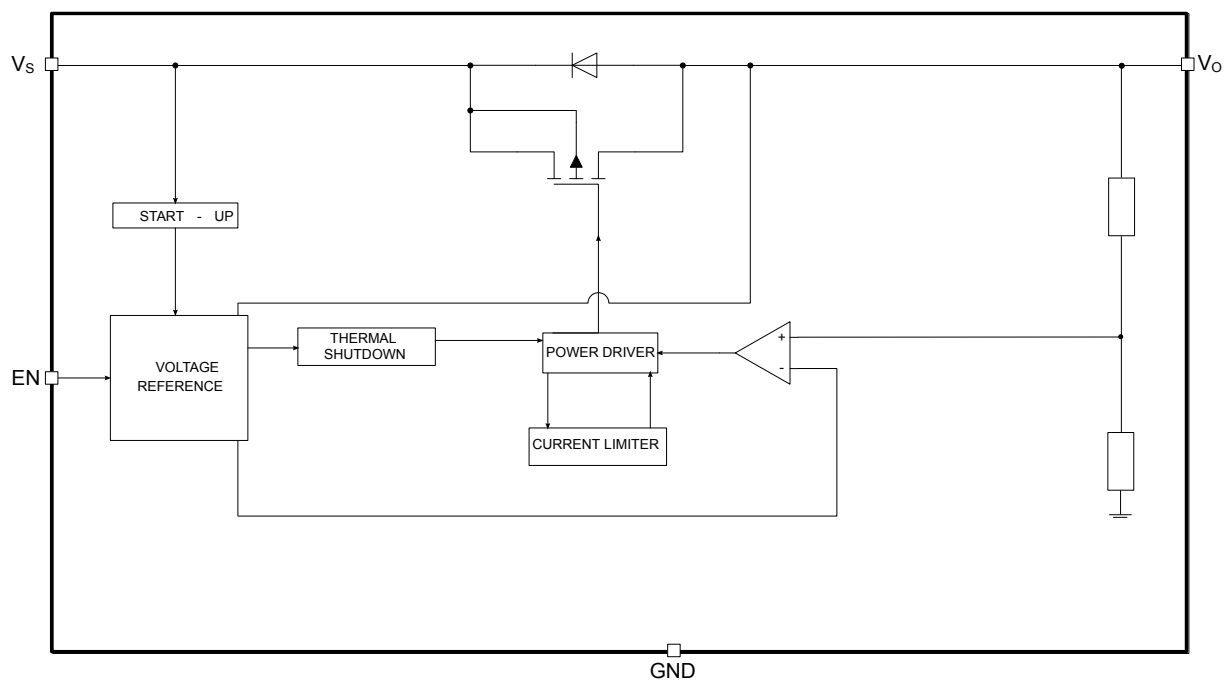
Description

L99VR03 is a low dropout linear voltage regulator designed for automotive applications available in VFDFN8L wettable flanks and PWSSO12 package. The LDO delivers up to 300 mA of load current and consumes as low as 800 nA of quiescent current when the regulator is disabled and only 3.5 μ A quiescent current at no load. The device is quite suitable for standby microprocessor control-unit systems, especially in automotive applications. The input voltage operating range is up to 40 V. The L99VR03 features enable. The L99VR03 is available in different output voltage options (3.3 V or 5 V). High output voltage accuracy ($\pm 2\%$) is kept over wide temperature range, line and load variation. The regulator output current is internally limited so that the device is protected against short-circuit, as it features over temperature protection.

1 Block diagram and pin description

1.1 Block diagram

Figure 1. Functional block diagram



1.2 Pin description

Figure 2. Pin connection (top view)

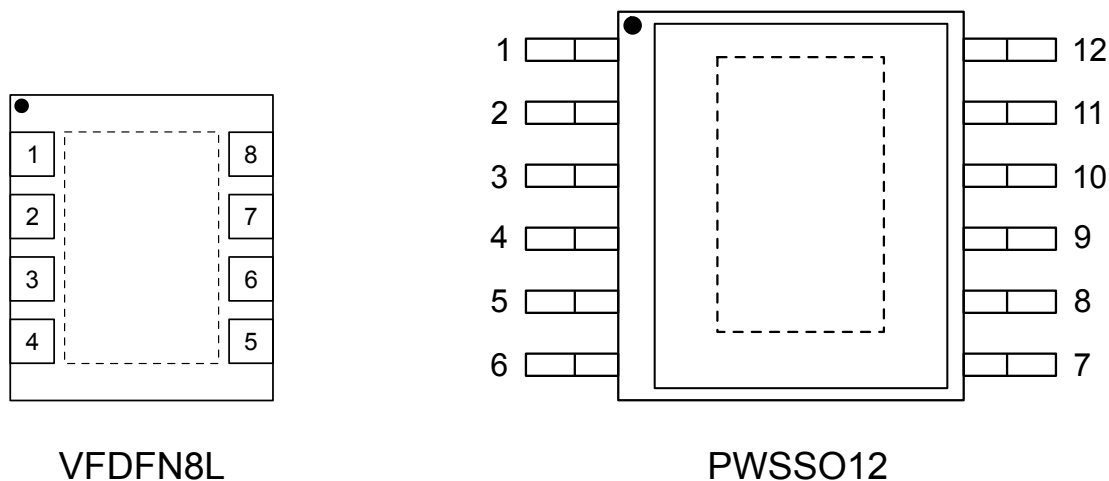


Table 1. VFDFN8L package pin function

#	Name	Function
1	V _S	LDO supply voltage
2	DNC	Do not connect, leave the pin floating
3	V _O	LDO output voltage
4	GND	Ground reference
5	DNC	Do not connect, leave the pin floating
6	DNC	Do not connect, leave the pin floating
7	DNC	Do not connect, leave the pin floating
8	EN	Enable input set V _{EN} : High = Turn on the device Low = Turn off the device EN pin cannot be left floating
TAB	TAB	Connected to the ground

Table 2. PWSSO12 package pin function

#	Name	Function
1	V _S	LDO supply voltage
2	DNC	Do not connect, leave the pin floating
3	V _O	LDO output voltage
4	GND	Ground reference
5	DNC	Do not connect, leave the pin floating
6	DNC	Do not connect, leave the pin floating
7	DNC	Do not connect, leave the pin floating
8	DNC	Do not connect, leave the pin floating
9	DNC	Do not connect, leave the pin floating
10	DNC	Do not connect, leave the pin floating
11	DNC	Do not connect, leave the pin floating
12	EN	Enable input set V _{EN} : High = Turn on the device Low = Turn off the device EN pin cannot be left floating
TAB	TAB	Connected to the ground

2 Electrical specifications

2.1 Absolute maximum ratings

Stressing the device above the rating listed in the [Table 3](#) may cause permanent damage to the device. These are stress ratings only and operation of the device at these or any other conditions above those indicated in the operating sections of this specification is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

Table 3. Absolute maximum ratings

Symbol	Parameter	Value	Unit
V_S	DC supply voltage	-0.3 to 28	V
V_S	Single pulse/ $t_{max} < 400$ ms “transient load dump”	40	V
V_O	DC output voltage	-0.3 to 7	V
I_O	DC output current	Internally limited	-
V_{EN}	Enable input	-0.3 to 28	V
VESD HBM	V_S pin vs GND, ESD HBM voltage level	± 4	kV
	ESD HBM voltage level	± 2	kV
VESD CDM	ESD CDM voltage level (CDM AEC-Q100-011)	± 500	V
	ESD CDM voltage level on corner pins (CDM AEC-Q100-011)	± 750	V

2.2 Thermal data

2.2.1 Thermal resistance

Table 4. Operation junction temperature

Symbol	Parameter	Value		Unit	Item
		VFDN8L	PWSS012		
$R_{thj-amb}$	Junction to ambient thermal resistance	32.5 ⁽¹⁾⁽²⁾	28.4 ⁽¹⁾⁽²⁾	°C/W	A.002

- $R_{thj-amb}$ based on a 4-layer JEDEC PCB (2S2P) test board with thermal vias (see the [Figure 22](#) and [Figure 24](#)).
- Measurements were performed according to JEDEC 51.2 in still air.

2.2.2 Thermal protection

Table 5. Temperature threshold

Symbol	Parameter	Test condition	Min.	Typ.	Max.	Unit	Item
$T_{prot}^{(1)}$	Thermal protection temperature		-	190	-	°C	A.003
T_{prot_hyst}	Thermal protection hysteresis		-	5	-	°C	A.004
T_J	Operating junction temperature	T_J	-40	-	175	°C	A.005
T_{stg}	Storage temperature	T_{stg}	-	-	150	°C	A.006

- Thermal protection is guaranteed by design and characterization.

2.3 Electrical characteristics

Values specified in this section are for $V_S = 4.5\text{ V}$ ($V_O = 3.3\text{ V}$) and $V_S = 6\text{ V}$ ($V_O = 5\text{ V}$) to 28 V , $T_J = -40\text{ °C}$ to $+150\text{ °C}$, unless otherwise stated.

Table 6. General characteristics

Symbol	Parameter	Test condition	Min.	Typ.	Max.	Unit	Pin	Item
V_{O_3V3}	Output voltage 3.3 V	$V_S = 4.5\text{ to }28\text{ V}$ $I_O = 0\text{ mA to }300\text{ mA}$	3.234	3.3	3.366	V	V_O	A.007
V_{O_5V}	Output voltage 5 V	$V_S = 6\text{ to }28\text{ V}$ $I_O = 0\text{ mA to }300\text{ mA}$	4.9	5	5.1	V	V_O	A.007
I_O	DC output current	$V_O = 3.3\text{ V}, V_O = 5\text{ V}$	-	-	300	mA	V_O	A.008
I_{short}	Short circuit current value	$V_O = 3.3\text{ V}, V_O = 5\text{ V}$	450	-	900	mA	V_O	A.009
$\Delta V_O/V_O$	Static line regulation	V_S is from 4.5 V for $V_O = 3.3\text{ V}$ or 6 V for $V_O = 5\text{ V to }40\text{ V}$ $I_O = 150\text{ mA}$	-	-	10	mV	V_S, V_O	A.010
$\Delta V_O/V_O$	Static load regulation	$I_O = 1\text{ mA to }300\text{ mA}, V_S = 14\text{ V}$ $V_O = 3.3\text{ V}, V_O = 5\text{ V}$	-	-	10	mV	V_O	A.011
V_{dp}	Drop voltage	$I_O = 300\text{ mA}$ $V_O = 5\text{ V}, V_O = 3.3\text{ V}$	-	0.55	1	V	V_S, V_O	A.012
PSRR	Power supply rejection ratio ⁽¹⁾	$V_S = 13.5\text{ V}, I_O = 300\text{ mA}$, frequency = 1 kHz, $V_O = 3.3\text{ V}$ $V_O = 5\text{ V}, C_O = 2.2\text{ }\mu\text{F}$	-	76	-	dB	V_S, V_O	A.013
I_{qn}	Current consumption with regulator disabled $I_{qn} = I_S - I_O$	$V_S = 4.5\text{ to }28\text{ V}$ for $V_O = 3.3\text{ V}$ $V_S = 6\text{ to }28\text{ V}$ for $V_O = 5\text{ V}$ EN = low	-	-	800	nA	V_S, V_O	A.014
I_{qn_LL}	Current consumption with regulator enabled $I_{qn_LL} = I_S - I_O$	$V_S = 4.5\text{ to }28\text{ V}$ for $V_O = 3.3\text{ V}$ $V_S = 6\text{ to }28\text{ V}$ for $V_O = 5\text{ V}$ $I_O = 0\text{ mA}, \text{EN} = \text{high}$	-	-	3.5	μA	V_S, V_O	A.023
I_{qn_O}	Current consumption with regulator enabled $I_{qn_O} = I_S - I_O$	$V_S = 4.5\text{ to }28\text{ V}$ for $V_O = 3.3\text{ V}$ $V_S = 6\text{ to }28\text{ V}$ for $V_O = 5\text{ V}$ $I_O = 1\text{ mA}, \text{EN} = \text{high}$	-	23	30	μA	V_S, V_O	A.015
I_{qn_50}	Current consumption with regulator enabled $I_{qn_50} = I_S - I_O$	$V_S = 4.5\text{ to }28\text{ V}$ for $V_O = 3.3\text{ V}$ $V_S = 6\text{ to }28\text{ V}$ for $V_O = 5\text{ V}$ $I_O = 50\text{ mA}, \text{EN} = \text{high}$	-	40	50	μA	V_S, V_O	A.016
I_{qn_150}	Current consumption with regulator enabled $I_{qn_150} = I_S - I_O$	$V_S = 4.5\text{ to }28\text{ V}$ for $V_O = 3.3\text{ V}$ $V_S = 6\text{ to }28\text{ V}$ for $V_O = 5\text{ V}$ $I_O = 150\text{ mA}, \text{EN} = \text{high}$	-	140	160	μA	V_S, V_O	A.017
I_{qn_300}	Current consumption with regulator enabled $I_{qn_300} = I_S - I_O$	$V_S = 4.5\text{ to }28\text{ V}$ for $V_O = 3.3\text{ V}$ $V_S = 6\text{ to }28\text{ V}$ for $V_O = 5\text{ V}$ $I_O = 300\text{ mA}, \text{EN} = \text{high}$	-	175	200	μA	V_S, V_O	A.018

1. Guaranteed by design - not tested.

Table 7. Enable characteristics

Symbol	Parameter	Test condition	Min.	Typ.	Max.	Unit	Pin	Item
V_{En_low}	EN input low voltage		-	-	0.7	V	EN	A.019
V_{En_hig}	EN input high voltage		2	-	-	V	EN	A.020

Table 8. UVLO characteristics

Symbol	Parameter	Test condition	Min.	Typ.	Max.	Unit	Pin	Item
V_S_{UVLO}	Ramp V_S down until the output turns OFF	$EN = V_S$	-	-	2.5	V	V_S	A.021
V_{UVLO_hyst}		$EN = V_S$	60	-	500	mV	V_S	A.022

Note:

All parameters are guaranteed in the junction temperature range -40 °C to 150 °C (unless otherwise specified); the L99VR03 device is still operative and functional at higher temperatures (up to 175 °C). Parameters limit at higher junction temperature than 150 °C may change respect to what is specified as per the standard temperature range. Device functionality at high junction temperature is guaranteed by characterization.

All parameters are guaranteed by design for V_O not reported in test condition.

Minimum input voltage values are achievable adopting an input ceramic capacitor: C5750X7R2A475M230KA - ceramic capacitor multistrata SMD, 4.7 µF, 100 V, ±20%, X7R, C series.

2.4 Electrical characteristics curves

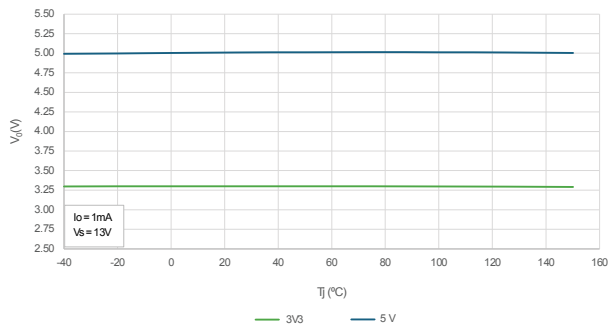
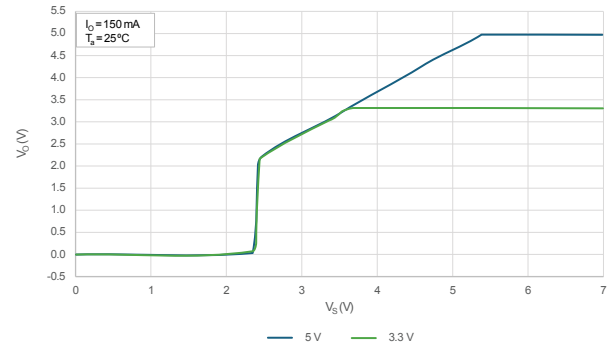
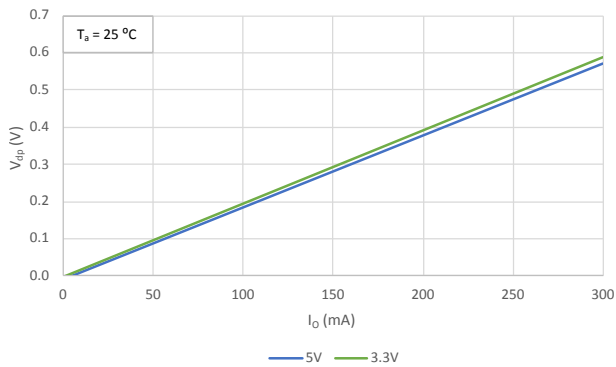
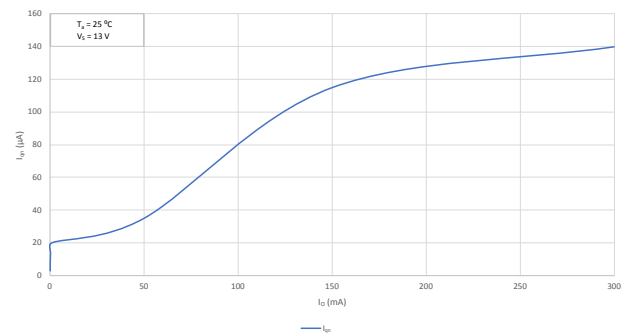
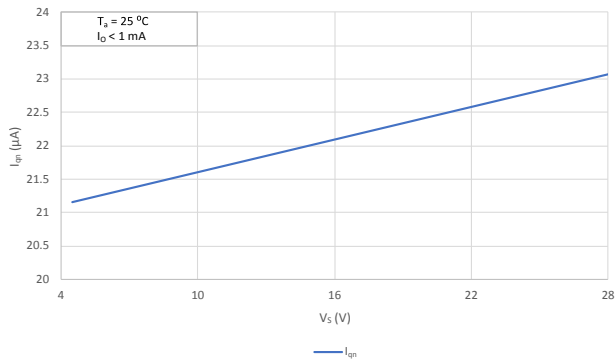
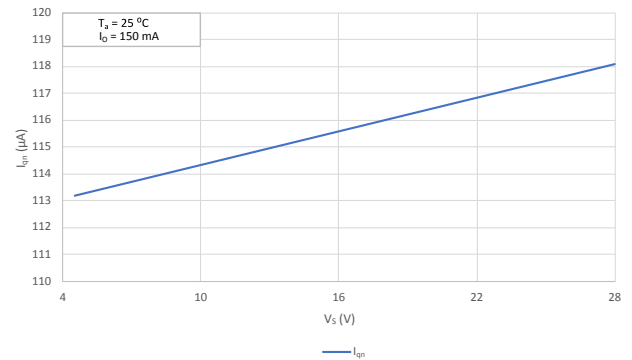
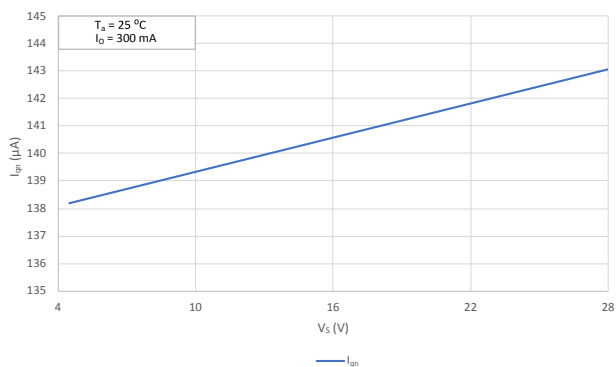
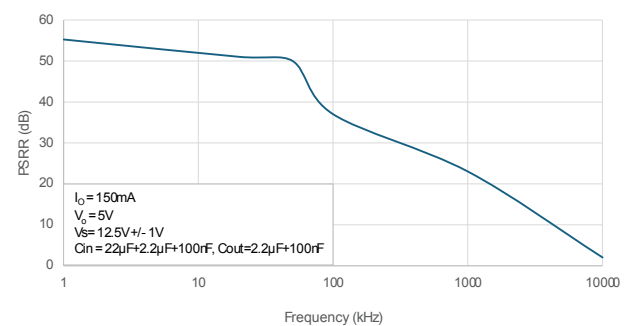
Figure 3. Output voltage vs T_J

Figure 4. Output voltage vs V_S

Figure 5. Drop voltage vs output current

Figure 6. Current consumption vs output current

Figure 7. Current consumption vs input voltage ($I_O < 1 \text{ mA}$)

Figure 8. Current consumption vs input voltage ($I_O = 150 \text{ mA}$)

Figure 9. Current consumption vs input voltage ($I_O = 300 \text{ mA}$)

Figure 10. PSRR


Figure 11. Output voltage vs enable voltage ($V_O = 3.3\text{ V}$)

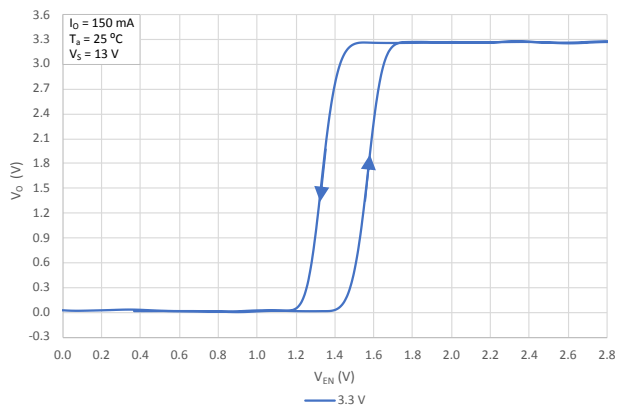


Figure 12. Output voltage vs enable voltage ($V_O = 5\text{ V}$)

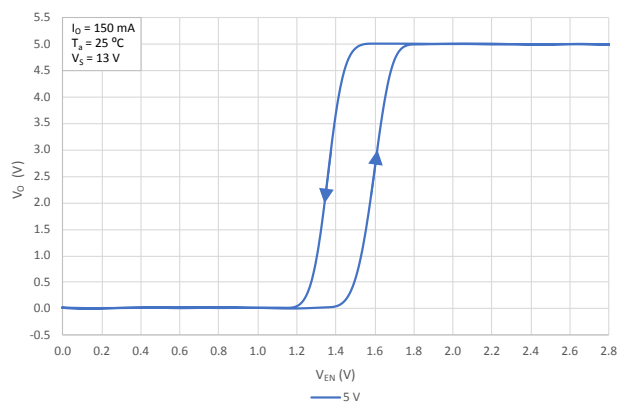


Figure 13. V_{EN_high} vs T_J

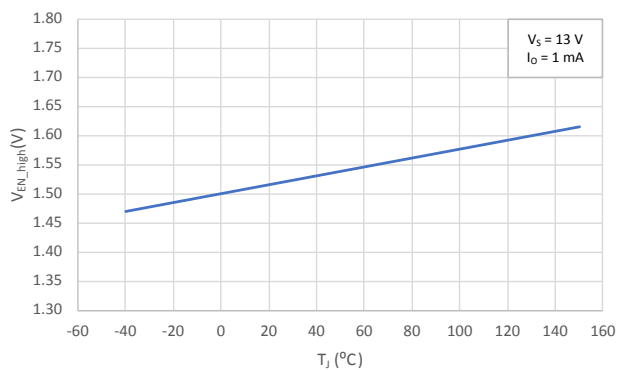


Figure 14. V_{EN_low} vs T_J

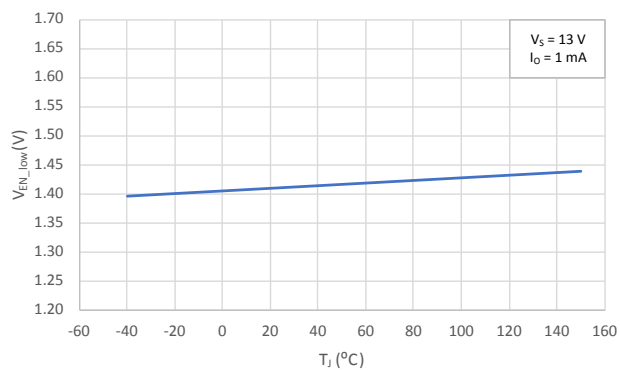
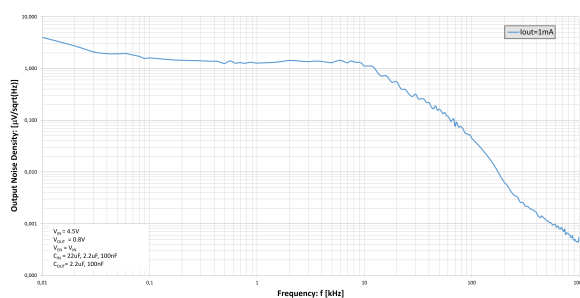
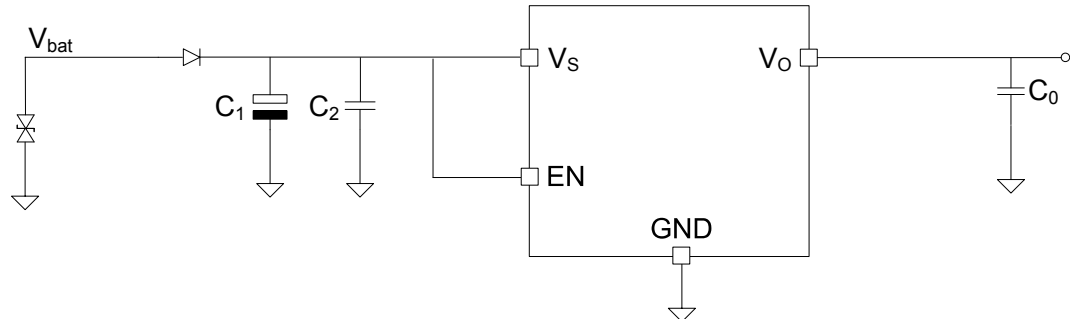


Figure 15. Output noise voltage



3 Application information

Figure 16. Application schematic

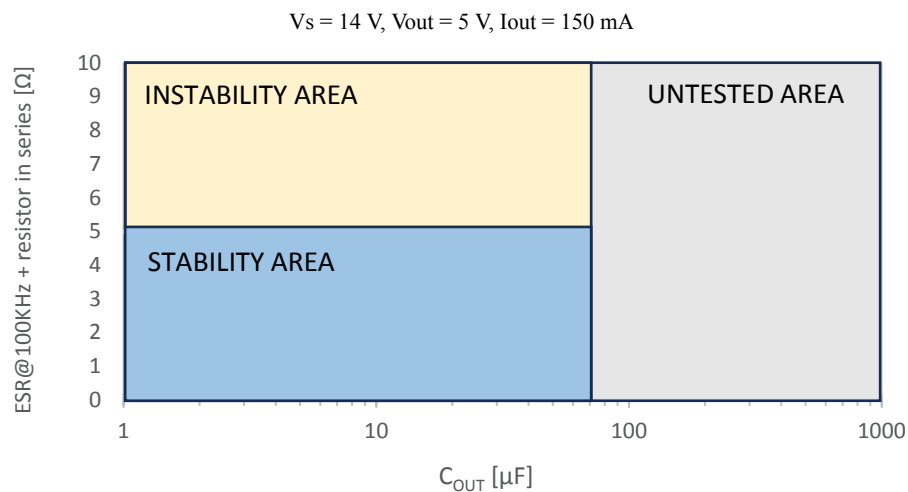


Input ceramic capacitor $C_2 \geq 1 \mu\text{F}$ is necessary for the regulator to operate properly.

The other input capacitor C_1 can be used as a backup supply for the application. The C_0 capacitor, connected to the output pin, is for bypassing to GND the high-frequency noise and it guarantees stability even during sudden line and load variations.

Tiny output capacitors reduce board space and BOM cost: stable operation with $2.2 \mu\text{F}$ capacitor min, $4.7 \mu\text{F}$ recommended to improve load transient response. $5 \Omega \geq \text{ESR} \geq 10 \text{ m}\Omega$.

Figure 17. Stability plane



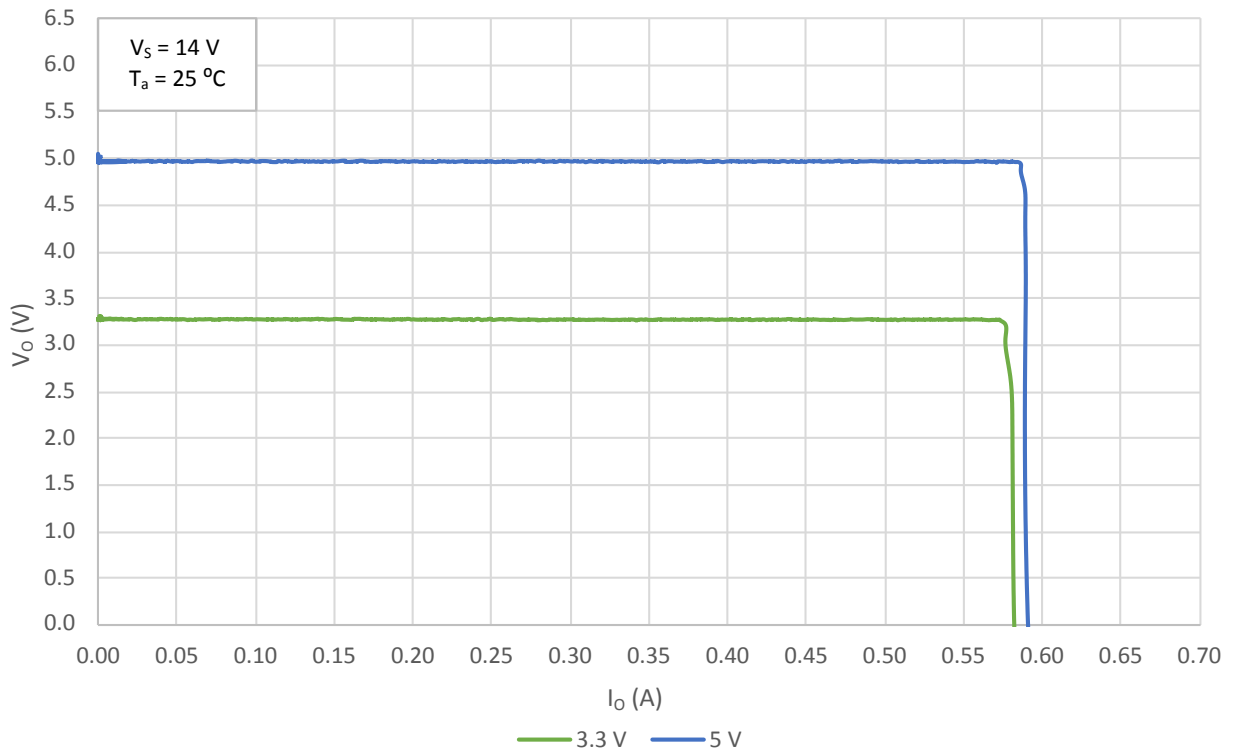
3.1 Voltage regulator

The voltage regulator uses a p-channel MOS transistor as a regulating element. With this structure, a very low dropout voltage at current up to $I_O = 300 \text{ mA}$ is obtained. The high-precision of the output voltage ($\pm 2\%$) is obtained with a pretrimmed reference voltage. The voltage regulator automatically adapts its own quiescent current to the output current level. In light load conditions, the quiescent current goes down to $I_{q_LL} = 3.5 \mu\text{A}$. L99VR03 operates with reduced input voltage (post regulation) minimizing the internal power dissipation and maximizing the output current. During initial power-up, after a thermal shutdown and a short to ground event, the regulator has a soft start incorporated to control initial current through the pass element and the output capacitor.

3.2 Output current limitation

Output current limitation is present to protect the regulator and the application from overload condition, such as short to ground.

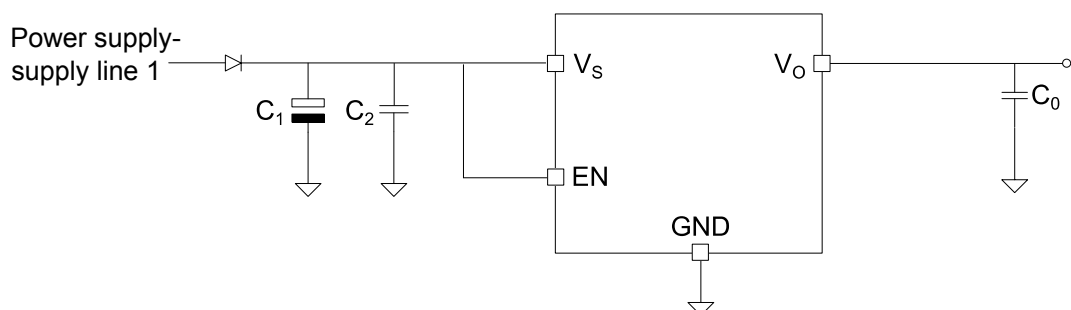
Figure 18. Behavior of output current versus regulated voltage V_O



3.3 Enable

The L99VR03 is enabled/disabled by the enable input. With the EN pin above V_{En_high} and the input voltage above V_{S_UVLO} , the device becomes active with a stable regulated output voltage. With the EN pin below V_{En_low} the device is disabled, reducing the quiescent current as low as 800 nA. The embedded hysteresis (V_{En_hyst}) avoids an undefined state of the device in case of slow ramp up signals applied to the EN input. It may happen that the enable pin must be driven by components supplied at a voltage different from the regulator supply voltage. In this case the EN input pin must be set high only once $V_S > 1.5$ V. A solution to drive the enable pin is depicted in the Figure 19.

Figure 19. Typical example of enable control

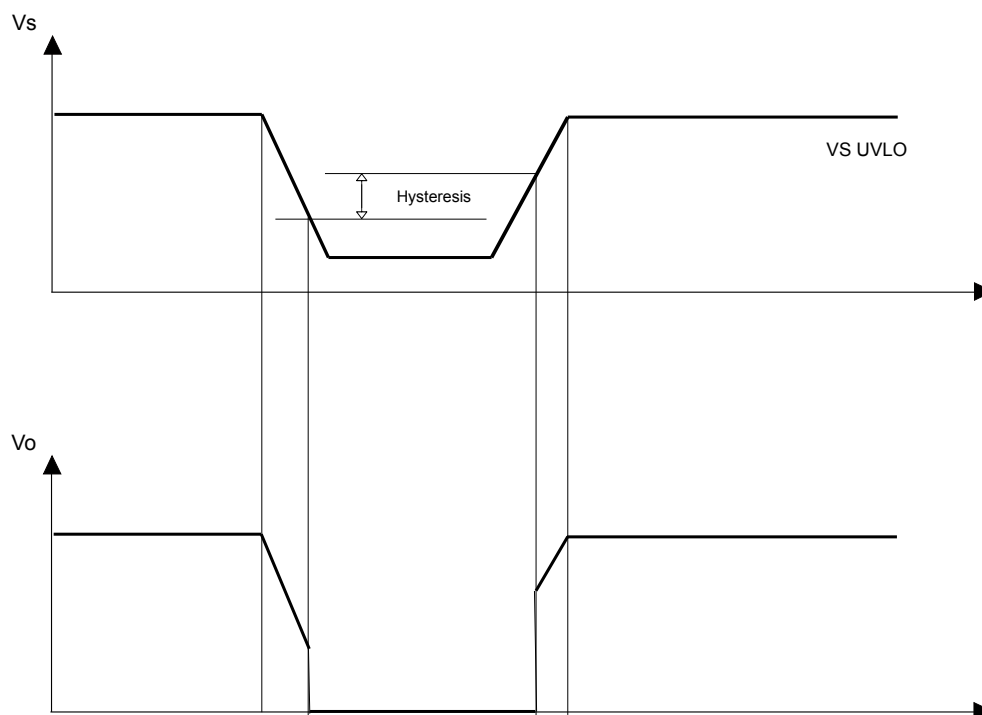


In any case, since the enable input voltage is linked to the maximum DC supply voltage (V_S) applied to the L99VR03 (-0.3 V to 28 V), special care must be adopted in driving the EN pin to avoid exceeding the absolute maximum rating.

3.4 Undervoltage lockout UVLO

The undervoltage lockout (UVLO) circuit allows to turn off the regulator element if the input voltage drops below the internal threshold, $V_{S\ UVLO}$, avoiding undesired unknown output state during low input voltage. When the input voltage is above the $V_{S\ UVLO}$ threshold, the regulating element is again turned on. If the input voltage has a negative transient which drops below the UVLO threshold and recovers, the regulator turns off and powers up with a normal power-up sequence once the input voltage is above the required levels.

Figure 20. Undervoltage lock out on output voltage



Not in scale

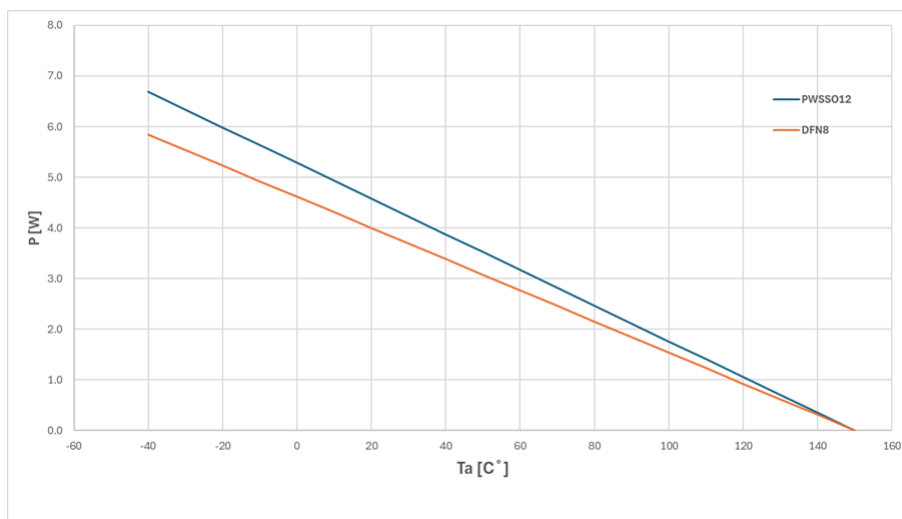
3.5 Thermal protection

Thermal protection acts when the junction temperature reaches 190 °C typical. At this point, the output of the IC shuts down. As soon as the junction temperature falls below the thermal hysteresis value, the device starts working again.

In order to calculate the maximum power that the device can dissipate, keeping the junction temperature below the maximum operating value, the following formula is used:

$$P_{\text{DMAX}} = (150 - T_{\text{AMB}}) / R_{\text{thj-amb}}$$

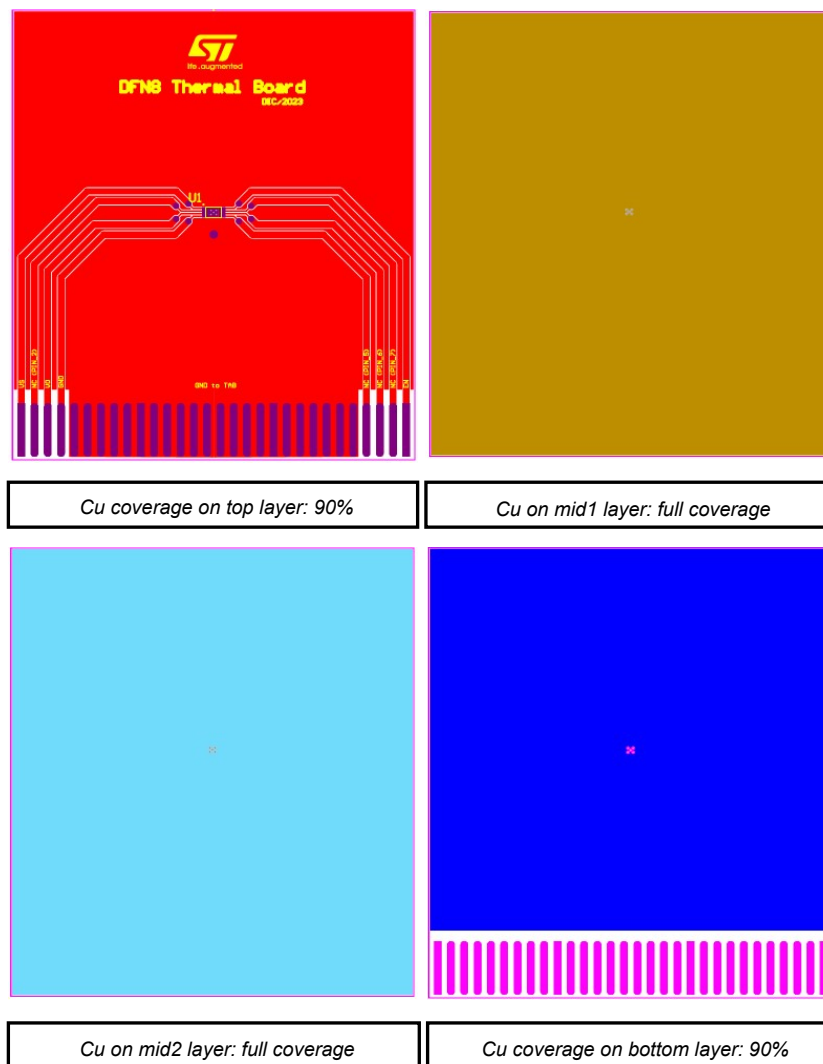
Figure 21. Derating curve



4 Package and PCB thermal data

4.1 VFDFN8 thermal data

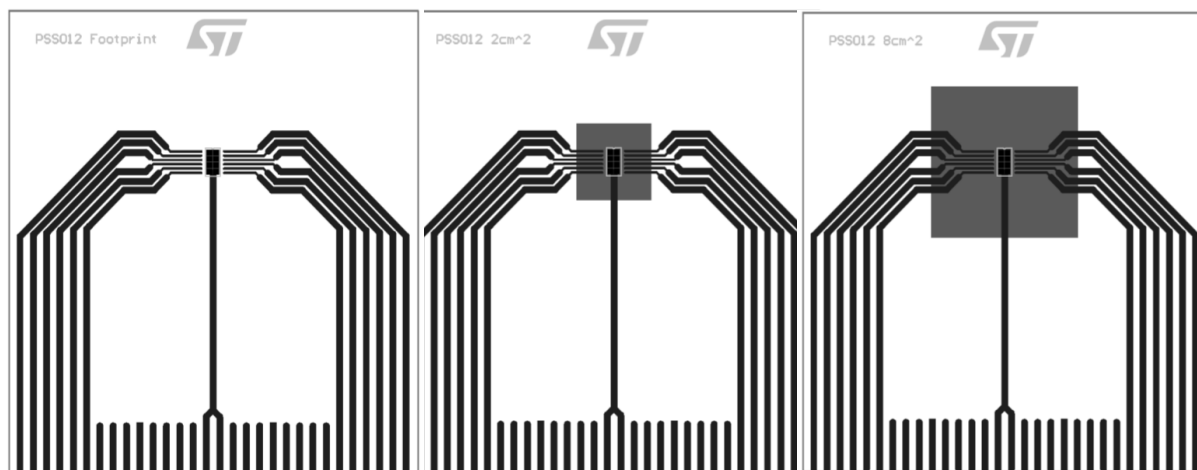
Figure 22. VFDFN8 PC board



- Board finish thickness 1.6 mm $\pm 10\%$
- Board four layers
- Board dimension 77 x 86 mm
- Board Material FR4
- Cu thickness 0.070 mm (outer layers)
- Cu thickness 0.035 mm (inner layers)
- Thermal vias separation 1.2 mm
- Thermal via diameter 0.3 mm ± 0.08 mm
- Cu thickness on vias 0.025 mm
- Footprint dimension 1.5 x 1.3 mm

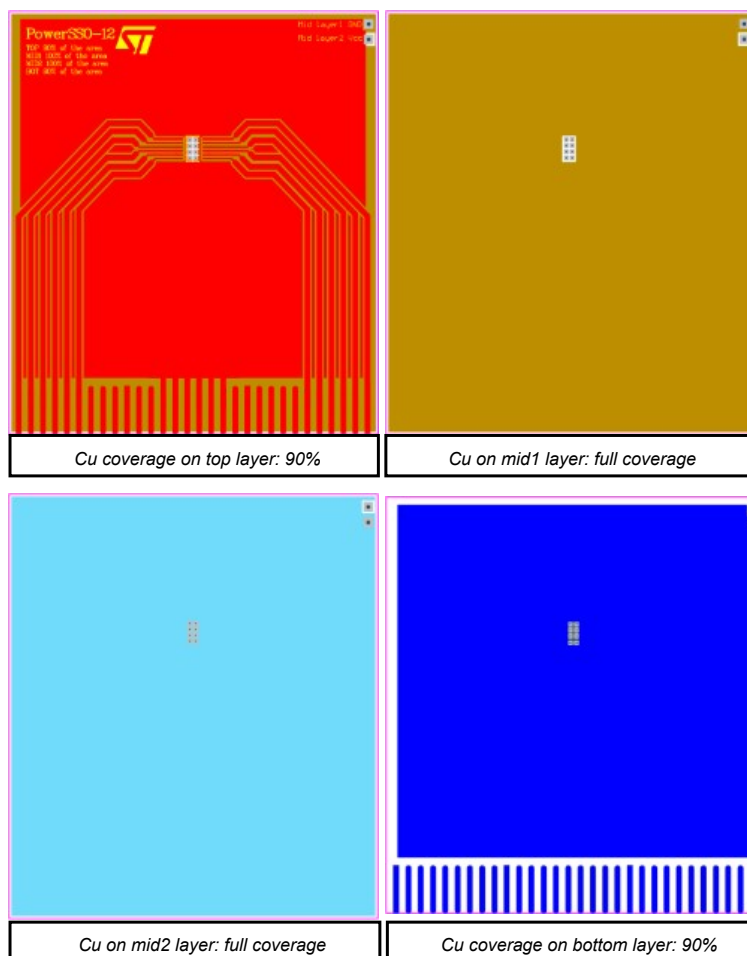
4.2 PWSSO12 thermal data

Figure 23. PWSSO12 PCB 2 layers

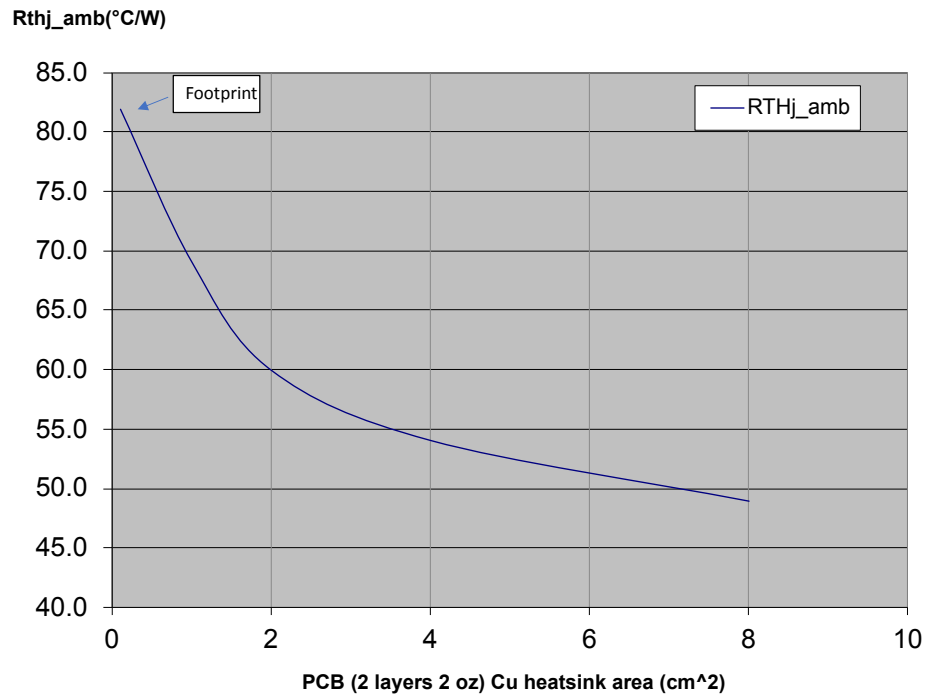
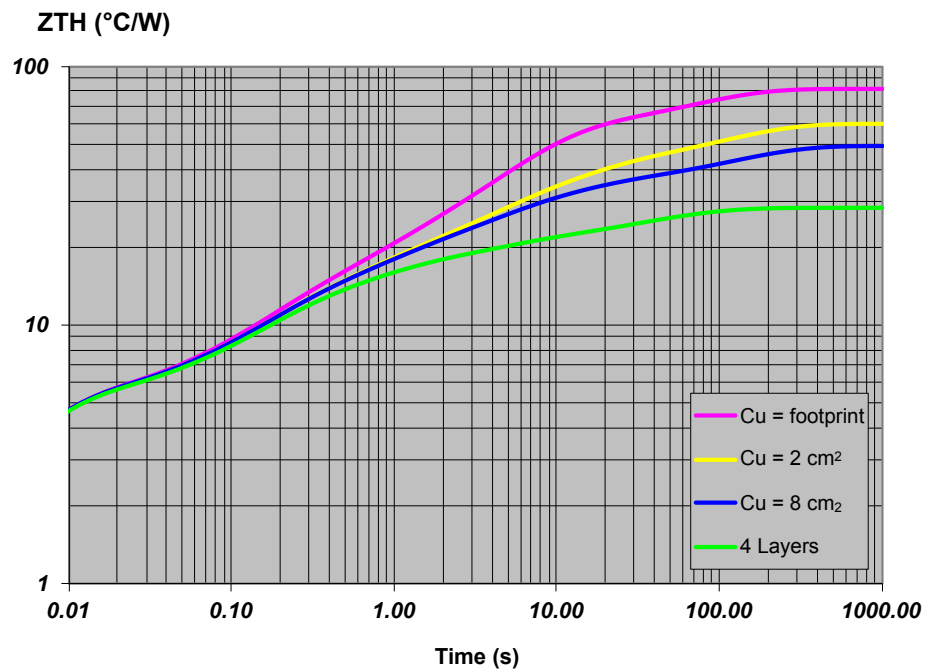


- Board finish thickness 1.6 mm $\pm 10\%$
- Board two layers
- Board dimension 77 x 86 mm
- Board Material FR4
- Cu thickness 0.070 mm (outer layers)
- Cu thickness 0.035 mm (inner layers)
- Thermal vias separation 1.2 mm
- Thermal via diameter 0.3 mm ± 0.08 mm
- Cu thickness on vias 0.025 mm
- Footprint dimension 2.2 x 3.9 mm

Figure 24. PWSSO12 PCB 4 layers



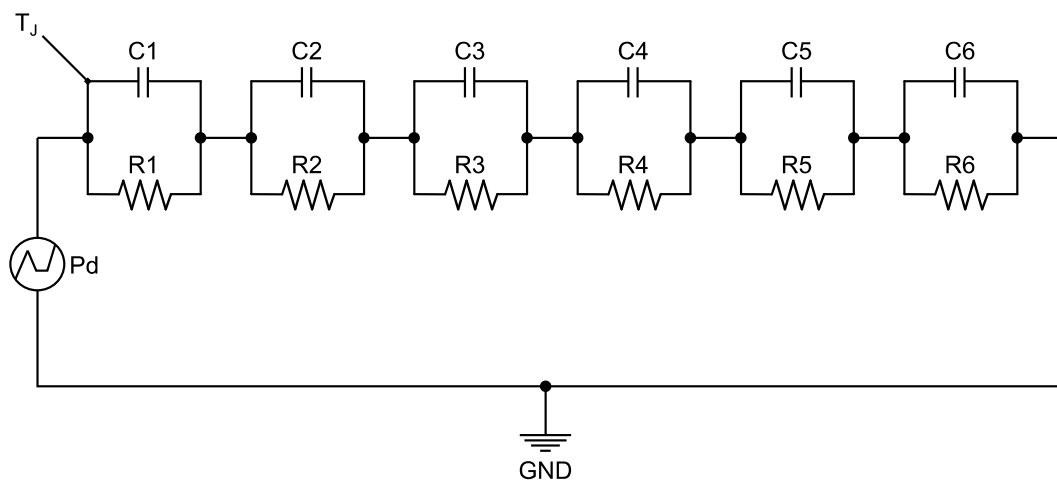
- Board finish thickness 1.6 mm $\pm 10\%$
- Board four layers
- Board dimension 77 x 86 mm
- Board Material FR4
- Cu thickness 0.070 mm (outer layers)
- Cu thickness 0.035 mm (inner layers)
- Thermal vias separation 1.2 mm
- Thermal via diameter 0.3 mm ± 0.08 mm
- Cu thickness on vias 0.025 mm
- Footprint dimension 2.2 x 3.9 mm

Figure 25. $R_{thj-amb}$ vs PCB copper area in still air condition - PWSSO12

Figure 26. Thermal impedance curves junction to ambient - PWSSO12


Pulse calculation formula:

$$Z_{TH\delta} = R_{TH} \cdot \delta + Z_{THtp}(1 - \delta) \quad (1)$$

 Where: $\delta = tp/T$

Figure 27. Thermal fitting model of a V_{reg} - PWSSO12

Table 9. Thermal parameter - PWSSO12

Thermal parameters	2 layer PCB			4L
	FP	2 CM	8 CM	
R1 (°C/W)	4.9	-	-	-
R2 (°C/W)	5	-	-	-
R3 (°C/W)	6	-	-	-
R4 (°C/W)	18	9	8	4.5
R5 (°C/W)	22	15	10	4
R6 (°C/W)	26	20	15	4
C1 (W·s/°C)	0.001	-	-	-
C2 (W·s/°C)	0.03	-	-	-
C3 (W·s/°C)	0.1	-	-	-
C4 (W·s/°C)	0.4	0.4	0.4	0.8
C5 (W·s/°C)	0.27	0.8	1	7
C6 (W·s/°C)	3	6	9	15

5 Package information

To meet environmental requirements, ST offers these devices in different grades of **ECOPACK** packages, depending on their level of environmental compliance. ECOPACK specifications, grade definitions, and product status are available at: www.st.com. ECOPACK is an ST trademark.

5.1 VFDFN8 (3x2x0.9 mm 8L wettable flanks) package information

Figure 28. VFDFN8 (3x2x0.9 mm 8L wettable flanks) package outline

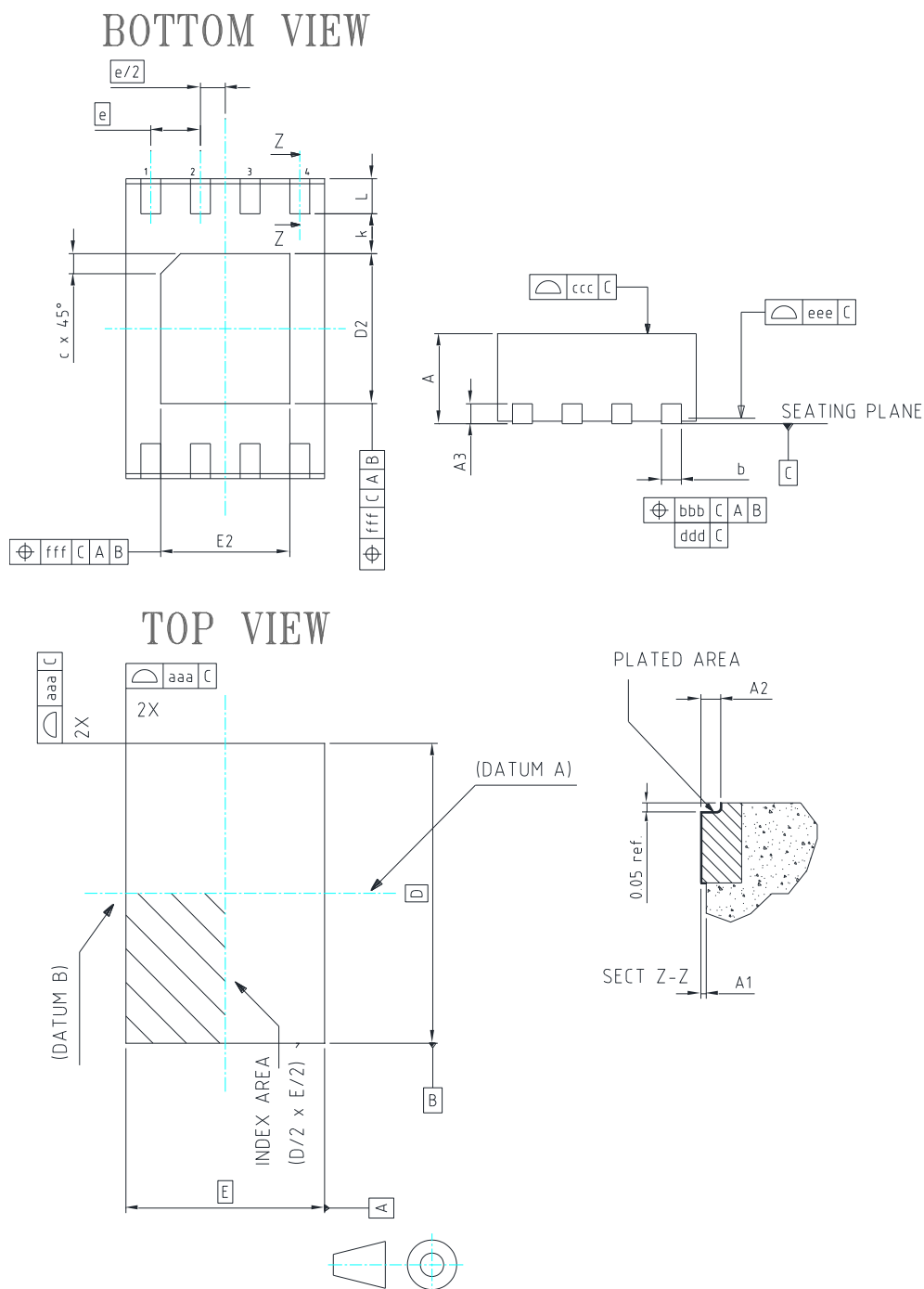


Table 10. VFDFN (3x2x0.9 mm 8L wettable flanks) package mechanical data

Symbol	Dimensions in mm		
	Min.	Typ.	Max.
A	0.80	0.90	1.00
A1	0.00	0.02	0.05
A2	0.100	-	-
A3	0.203 REF		
L	0.25	0.35	0.45
b	0.15	0.20	0.25
D	-	3.00 BSC	-
E	-	2.00 BSC	-
D2	1.40	1.50	1.60
E2	1.20	1.30	1.40
e	0.5 REF		
N	8		
Tolerance of form and position			
aaa	0.05		
bbb	0.10		
ccc	0.10		
ddd	0.05		
eee	0.08		
fff	0.10		

5.2 PWSSO12 (4.9x3.9x1.5 mm exposed pad down) package information

Figure 29. PWSSO12 (4.9x3.9x1.5 mm exposed pad down) package outline

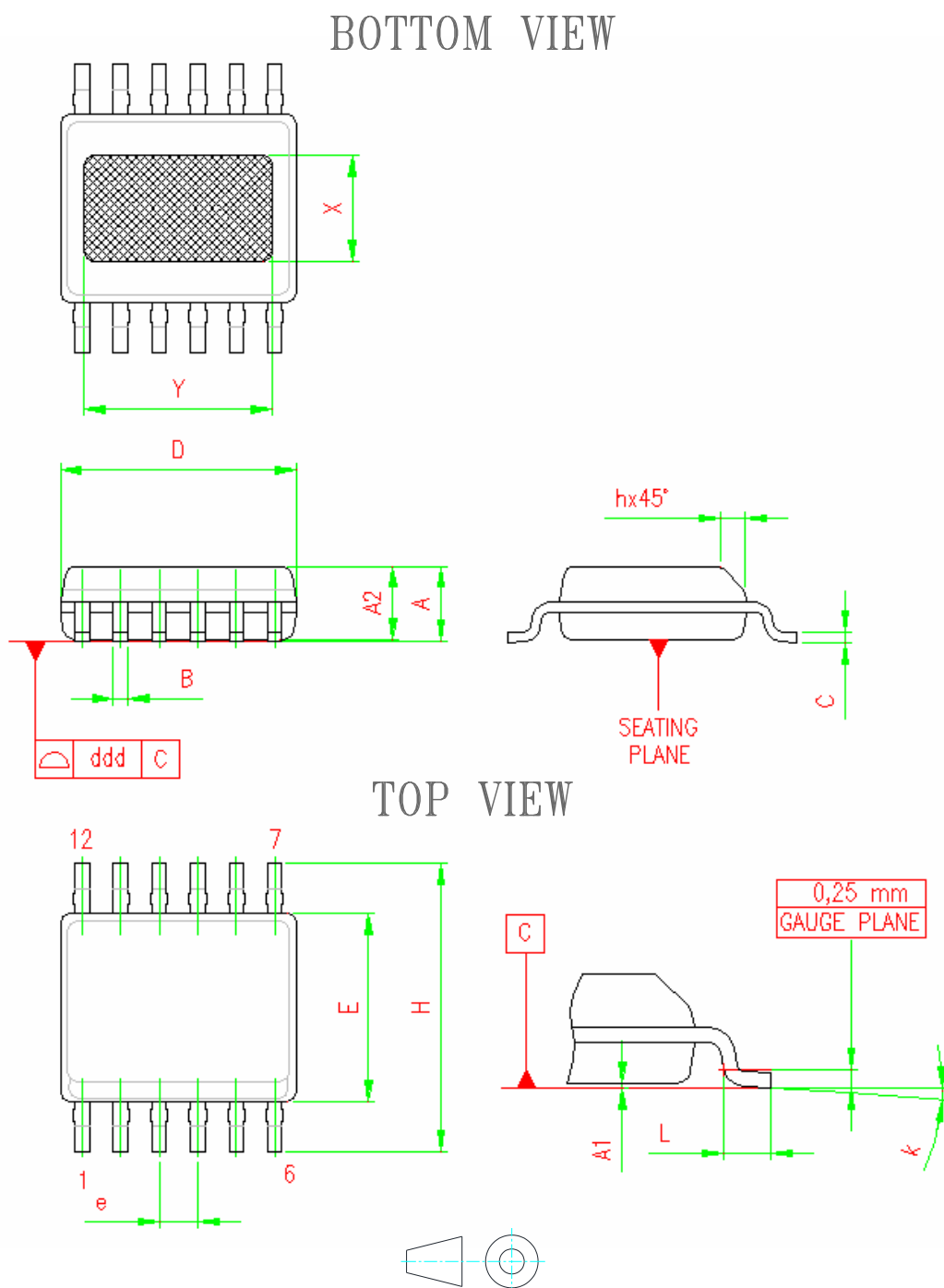
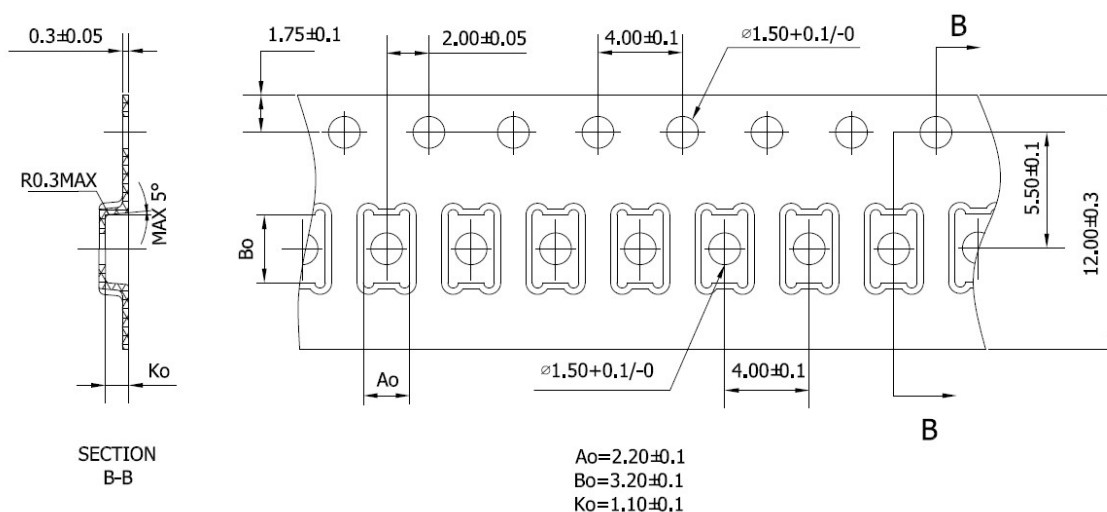


Table 11. PWSSO12 (4.9x3.9x1.5 mm exposed pad down) package mechanical data

Symbol	Dimensions in mm		
	Min.	Typ.	Max.
A	1.25	-	1.70
A1	0.00	-	0.10
A2	1.10	-	1.60
B	0.2	-	0.41
C	0.190	-	0.25
D	4.80	-	5.00
E	3.80	-	4.00
e	-	0.80	-
H	5.80	-	6.20
h	0.25	-	0.50
L	0.40	-	1.27
k	0d	-	8d
X	2.20	-	2.80
Y	2.90	-	3.50
ddd	-	-	0.10

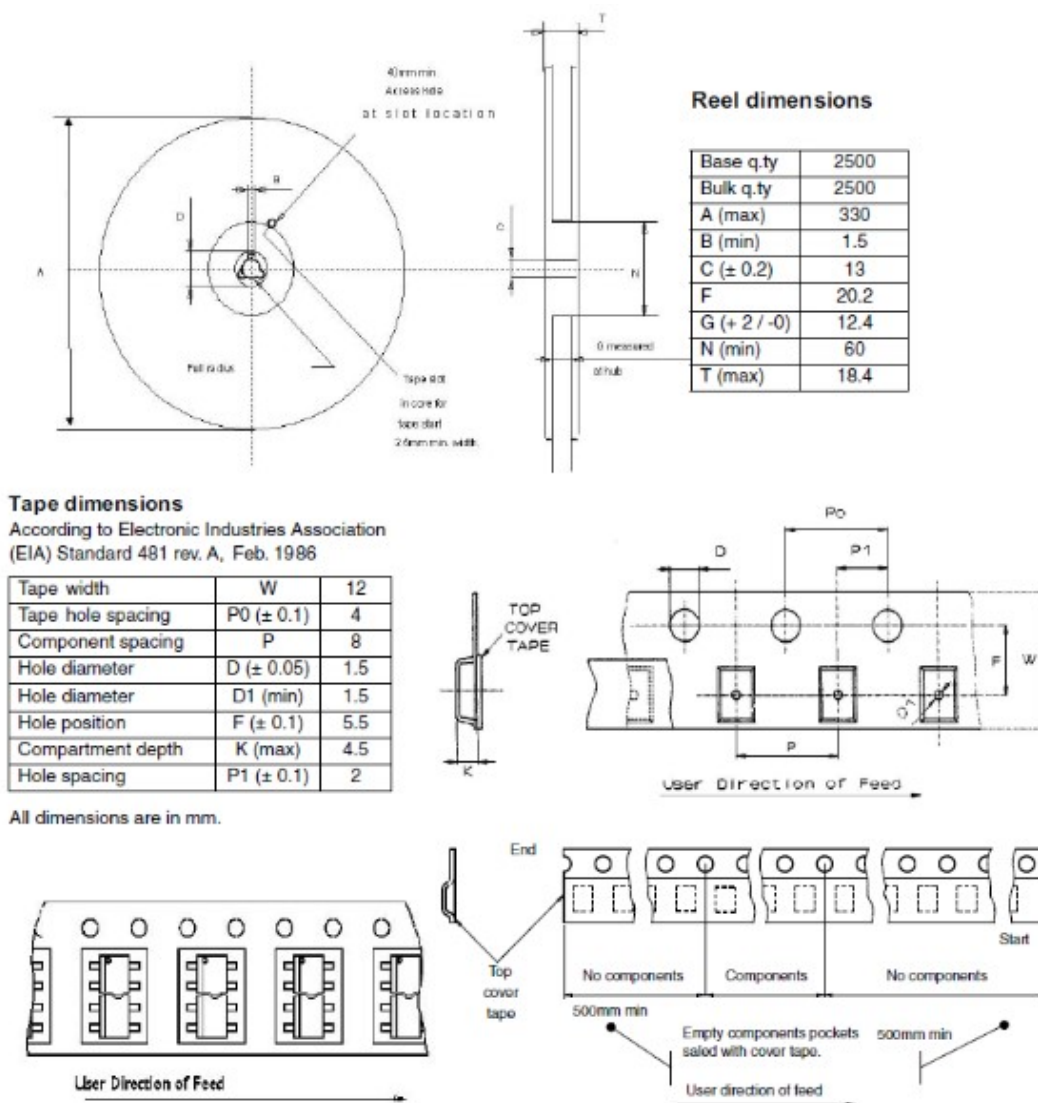
5.3 VFDFN8 packaging information

Figure 30. VFDFN8 tape and reel shipment



5.4 PWSSO12 packaging information

Figure 31. PWSSO12 tape and reel shipment



Revision history

Table 12. Document revision history

Date	Version	Changes
04-Dec-2024	1	Initial release.
27-Oct-2025	2	Added new package VFDFN8L, new Section 1.2: Pin description Section 3.5: Thermal protection, new Section 5.1 and Section 5.3.
13-Apr-2026	3	Added Figure 15

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